

(1)

I.

WIPS

1987 1 1

2007 4 30

가 , , ,

[연재 일정 안내]

2008. 1	(1)	1
	SoC(1)	
2008. 2	(1)	2
	SoC(2)	
2008. 3	(2)	3
	SoC(3)	
2008. 4	(3)	4
	SoC(4)	
2008. 5	(4)	1
	(1)	
2008. 6	(1)	2
	(2)	
2008. 7	(2)	3
	(3)	
2008. 8	(3)	4
	(4)	
2008. 9	(4)	1
	(1)	
2008. 10	(1)	2
	(2)	
2008. 11	(2)	3
	(3)	
2008. 12	(3)	4
	(4)	

e (www.patentmap.or.kr)

가	- ,
	- + + 1
	- (Applications), (Granted)
	- +
	- PAJ
	- + + 1
	- EP-A(Applications), EP-B(Granted)
	- + 1

가

, , / , /
recycling
SI



SoC(1)

I.
 1.1.
 가 SoC (reconfigurable)
 SoC Configurable
 SoC computing, platform
 SoC , ASIC
 DSP 가



I-1 SoC

SoC SoC

SoC		fine grain
		coarse grain
		multi-granularity
		loosely coupled
		tightly coupled
		bus coupled
		dynamic
		static

	/	
	/	/
	SDR	
	RF	RF
	I-1	SoC

1.2. SoC
 SoC (application specific integrated circuit, ASIC) (Microprocessor)
 (flexibility)
 (Programmable DSP)
 가 (Run Time Reconfigurable)

가

1)

(Fine Grain Architecture),
 (Coarse Grain Architecture),
 (Multi Grain Architecture)
 (Reconfiguration)
 가
 , 2 가
 (Reconfigurable Array)

가 가
(Word)

2)

loosely coupled, tightly coupled, bus coupled

loosely coupled
(peripheral)

, bus coupled

1.3.

가

가

1)

dynamic

static

static

dynamic

가

가

2)

,

SoC

1.4.

/

,

1.5.

SDR

RF
SDR

가

SDR

SDR

가

(1)

I.

1.1. 가

가

, DNA, SPR(surface plasm on resonance),

MEMS (SERS), FET,

		(TIR)
		(SERS)
		FET
		QCM(quartz crystal microbalance)
		(microfluidics)
	MEMS	(Lab - on - a - chip)

, QCM(quartz crystal microbalance), (Microfluidics), (Lab on a chip)

가

1.2.

(SERS), (TIR)

, MEMS

1.3.

가

가

가

가

가

1.4. MEMS

Micro Electro Mechanical System(MEMS)

가
MEMS
가

가
가

